



SAMPLE APPROVE SHEET

Customer Name:_____

Product description: <u>SMD3030RGB 6 LEAD 1.5W</u>

ProductName: CL-SFC3030RGB-B-05(1.5W)

Issue Date : 2023-03-03

Lens Color	С	Water Transparent		
	Т	Colored Transparent		
Code	D	White Diffused		
	E	Colored Diffused		

Customer confirmation	Checked by	Prepared by







Features And Benefits

- Designed for high current operation
- Low thermal resistance
- RGB 3n1 LED, High Power
- Pb-free reflow soldering application

Key Applications

- Indoor lighting
- Outdoor lighting
- Automotive
- Architectural lighting
- Industrial lighting
- Portable torch



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Typical Optical/ Electrical Characteristics @TJ=25°C							
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	
Forward Voltage Red	VF	IF=150mA	2.0		2.4	V	
Forward Voltage Green	VF	IF=150mA	3.0		3.4	V	
Forward Voltage Blue	VF	IF=150mA	2.8		3.4	V	
Reverse Current	IR	VR=5v		5		μΑ	
50% Power Angle	201/2	//		120		deg	
Recommend Forward	1-			150		m۸	
Current	IF			150			
Luminous Intensity Red	φv	IF=150mA	15		20	Lm	
Luminous Intensity Green	φv	IF=150mA	30		40	Lm	
Luminous Intensity Blue	φv	IF=150mA	8		15	Lm	
Junction temperature	TJ	//		125		°C	
Dominant wavelength Red	Тс	IF=150mA	620		630	nm	
Dominant wavelength Green	Tc	IF=150mA	520		530	nm	
Dominant wavelength Blue	Тс	IF=150mA	460		470	nm	
Thermal	_			0		°C /III	
Resistance, Junction to Case	KJP			ŏ		C/W	

Notes:1.Tolerance of measurement of forward voltage±0.1V.

2. Tolerance of measurement of peak Wavelength±2.0nm.

3.Tolerance of measurement of luminous intensity±5%.

Absolute Maximum Rating

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	150	mA
Peak Forward Current*	IFP	300	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	12	W
Operation Temperature	TOPR	-40~+80	°C
Storage Temperature	TSTG	-40~+100	°C
Lead Soldering		Max. 260 °C for 5sec Max.	
Temperature*	TSOL		

*IFP Conditions: Pulse Width≤10msec duty≤1/10

* All high power emitter LED products mounted on aluminum metal-core printed circuit board, can be lighted directly, but we do not recommend lighting the high power products for more than 5 seconds without a appropriate heat dissipation equipment.

*Re-flow,wave peak and soak-stannum soldering etc.is not suitable for this products.

*Suggest to solder it by professional high power LED soldering machine.

*Can use invariable-temperatur e searing-iron with soldering condition :<260 degree less than 3 seconds.

























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Note:

- LED bracket forming method: The pin of LED canbe bent where is at least 2mm out of LED colloid; Finishing the forming of LED bracket must be before soldering; Guarantee the gap between two pin of LED tallys with LED pads in PCB when forming;
- 2 Manual soldering: The tip temperature of soldering iron don't exceed300°C;soldering time don't exceed 3s and soldering position must be 3mm out of led colloid;
- 3 Static electricity and high volt can damage LED, The production whose Die material is InGaN must strictly required ESD, Must put on static glove and static fillet, soldering tool and the cover of device must connect the ground, soldering condition follows the related stating of production specification manual.
- 4 Protecting countermeasure when over current: Need add the protecting resistor in circuit in order to avoid damaging led due to big current and voltage fluctuation
- 5 LED installation method: LED can be stored for a year under the condition, the temperture of $5^{\circ}C \sim 35^{\circ}C$ and humidity of RH60%, These production must be re-inspected and tested before use if their storage time exceed a year.
- 6 If LED is exposed in air for a week under the condition,the temperature of 5 °C ~35°C, humidity of RH60%,must place the LED in the ambience of 65°C ±5°C for 24 hours.

